



# STPS41H100CG/CT/CR

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 20 A
$V_{RRM}$	100 V
$T_j$ (max)	175 °C
$V_F$ (max)	0.67 V

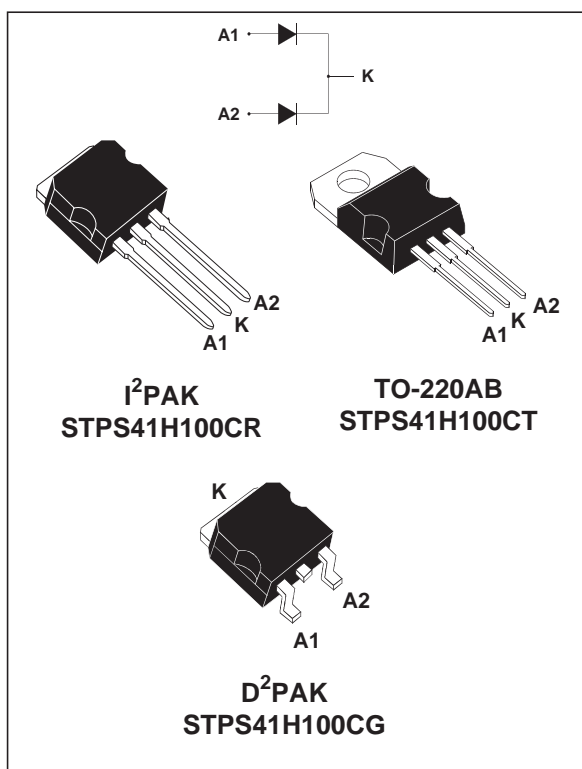
### FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW LEAKAGE CURRENT
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

### DESCRIPTION

Dual center tab Schottky rectifier suited for Switch Mode Power Supply and high frequency DC to DC converters.

Packaged in D<sup>2</sup>PAK, I<sup>2</sup>PAK and TO-220AB, this device is intended for use in high frequency inverters.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		100	V
$I_{F(RMS)}$	RMS forward current		30	A
$I_{F(AV)}$	Average forward current	$T_c = 150^\circ\text{C}$ $\delta = 0.5$	Per diode 20	A
			Per device 40	
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10$ ms sinusoidal	220	A
$I_{RRM}$	Peak repetitive reverse current	$t_p = 2$ $\mu\text{s}$ square $F = 1$ kHz	1	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1$ $\mu\text{s}$ $T_j = 25^\circ\text{C}$	18100	W
$T_{stg}$	Storage temperature range		- 65 to + 175	°C
$T_j$	Maximum operating junction temperature *		175	°C
$dV/dt$	Critical rate of rise reverse voltage		10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink

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## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	1.5	$^{\circ}\text{C}/\text{W}$
		Total	0.8	
$R_{th(c)}$	Coupling		0.1	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

## STATIC ELECTRICAL CHARACTERISTICS (per diode)

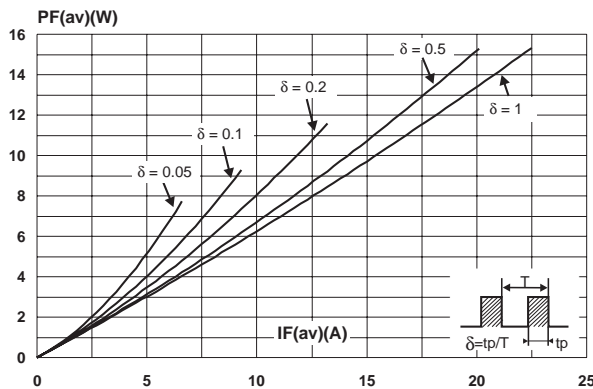
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			10	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$			3	10	mA
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 20\text{ A}$			0.80	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 20\text{ A}$		0.62	0.67	
		$T_j = 25^{\circ}\text{C}$	$I_F = 40\text{ A}$			0.90	
		$T_j = 125^{\circ}\text{C}$	$I_F = 40\text{ A}$		0.70	0.76	

Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

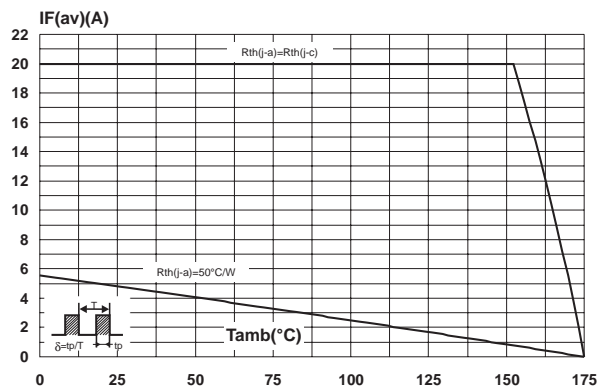
To evaluate the conduction losses use the following equation :

$$P = 0.58 \times I_{F(AV)} + 0.0045 I_{F(RMS)}^2$$

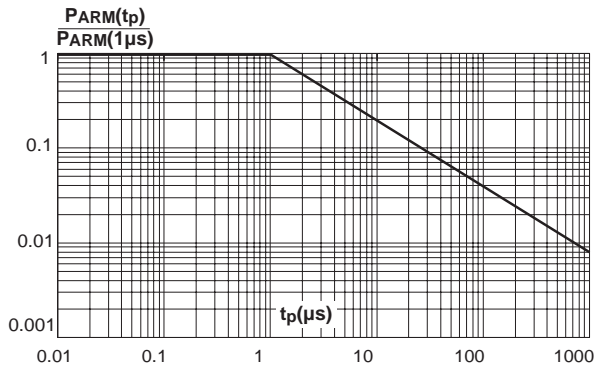
**Fig. 1:** Conduction losses versus average current.



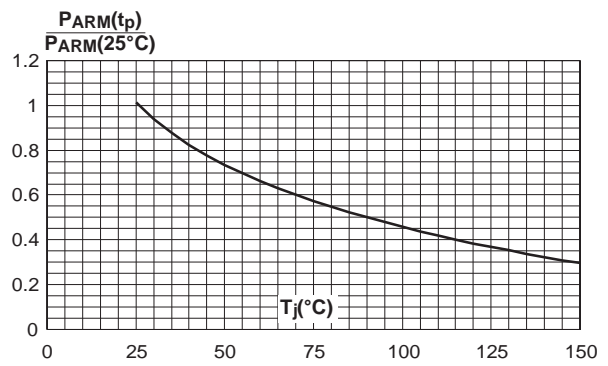
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



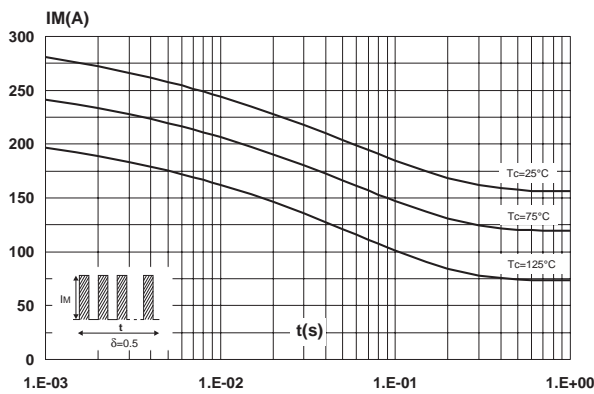
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



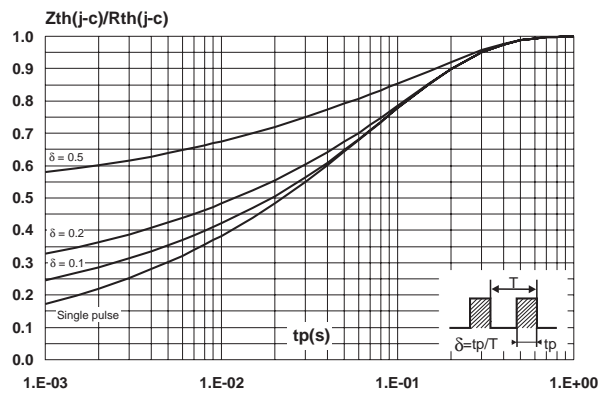
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



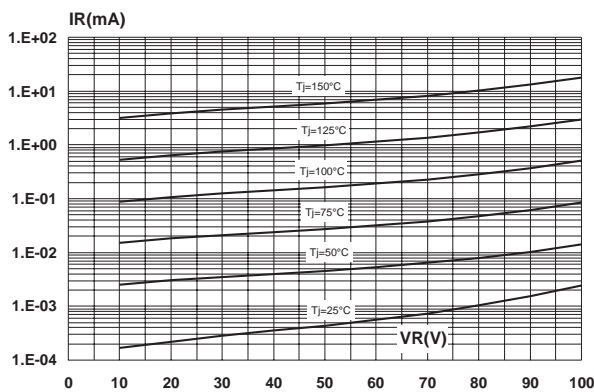
**Fig. 5:** Non repetitive surge peak forward current versus overload duration (maximum values).



**Fig. 6:** Relative variation of thermal impedance junction to case versus pulse duration.



**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values).



**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values).

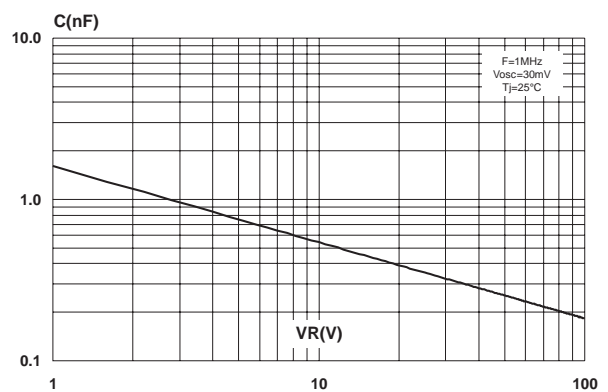


Fig. 9: Forward voltage drop versus forward current.

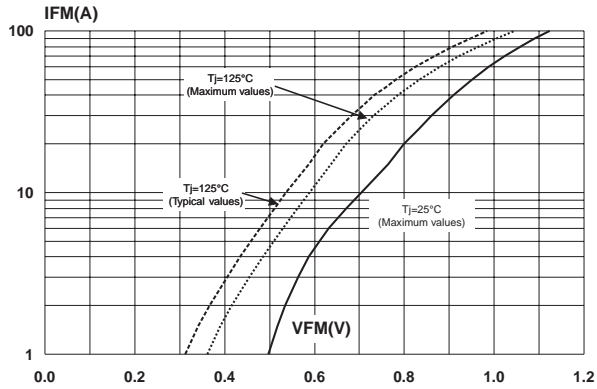
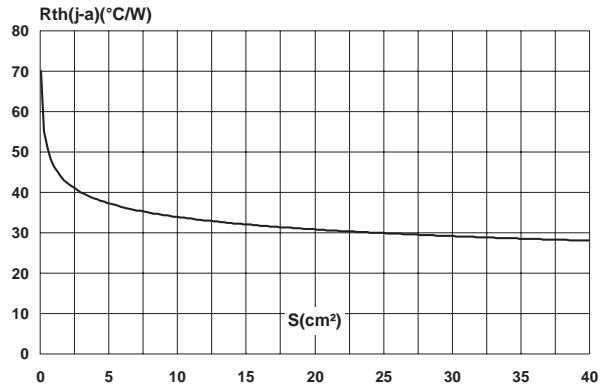
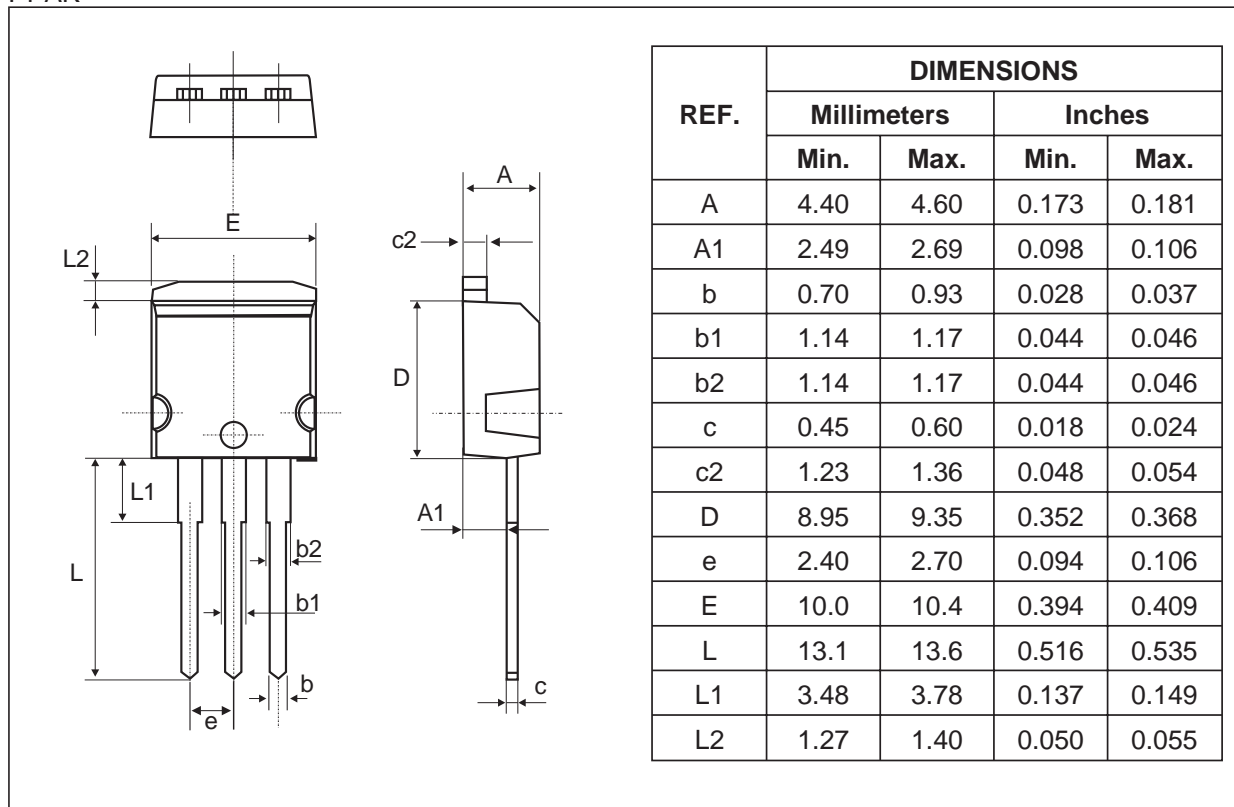


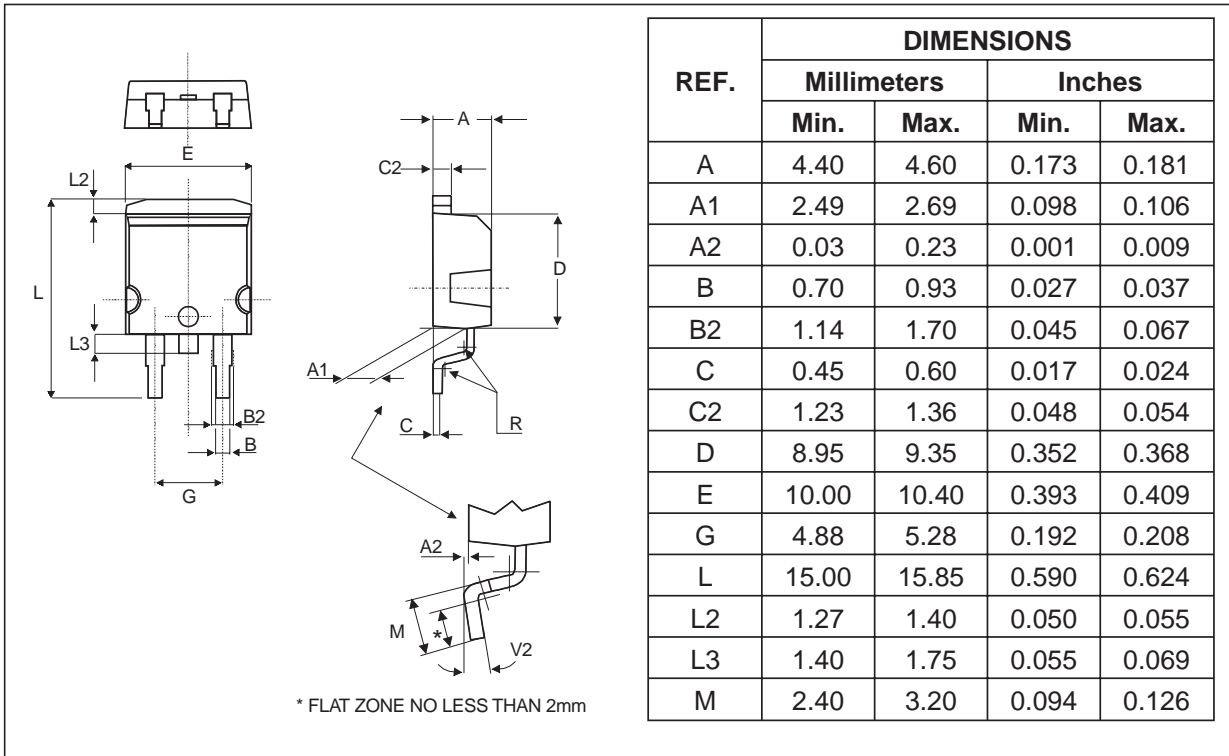
Fig. 10: Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu = 35µm). (STPS41H100CG only)



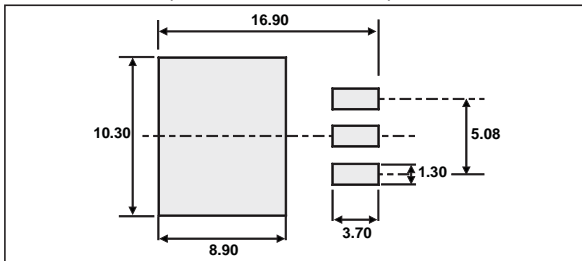
PACKAGE MECHANICAL DATA  
I<sup>2</sup>PAK



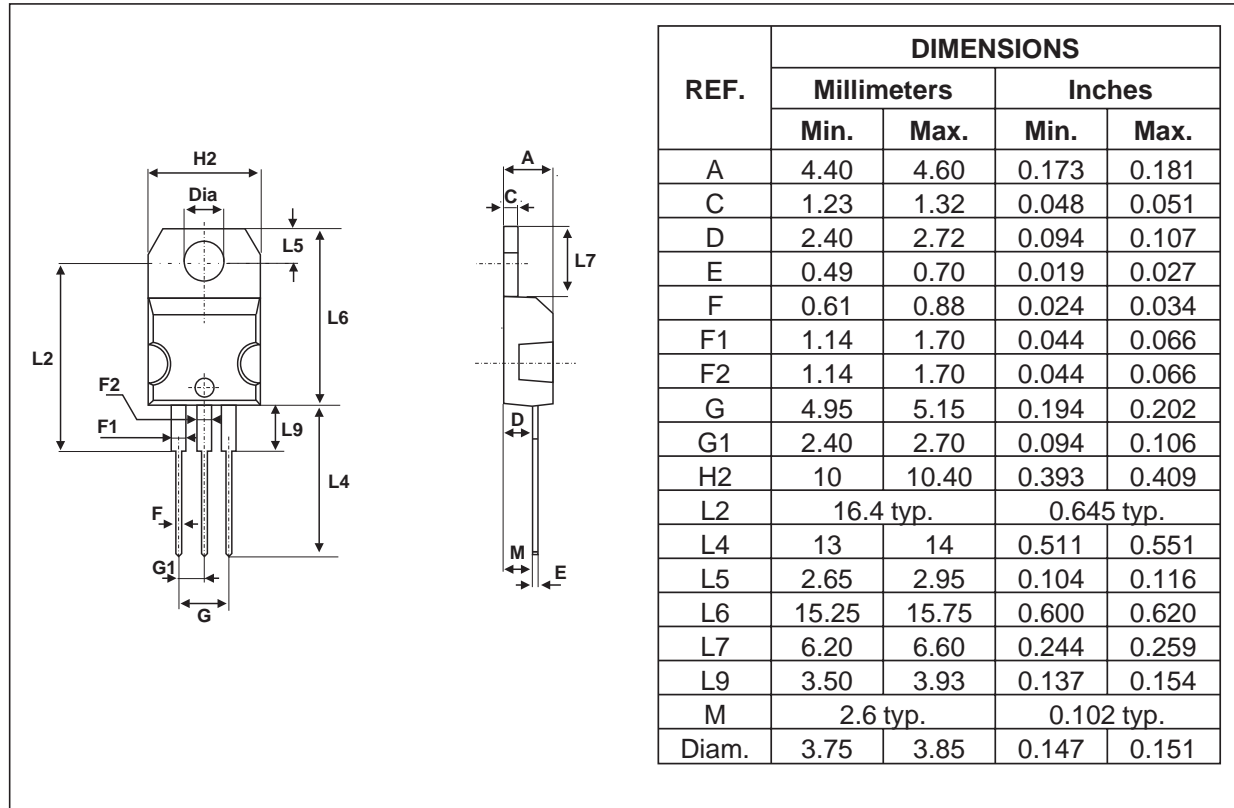
**PACKAGE MECHANICAL DATA**  
D<sup>2</sup>PAK



**FOOTPRINT (dimensions in mm)**



**PACKAGE MECHANICAL DATA**  
TO-220AB



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS41H100CT	STPS41H100CT	TO-220AB	2.20 g	50	Tube
STPS41H100CG	STPS41H100CG	D <sup>2</sup> PAK	1.48 g	50	Tube
STPS41H100CG-TR	STPS41H100CG	D <sup>2</sup> PAK	1.48 g	1000	Tape & reel
STPS41H100CR	STPS41H100CR	I <sup>2</sup> PAK	1.49 g	50	Tube

■ EPOXY MEETS UL94,V0

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